

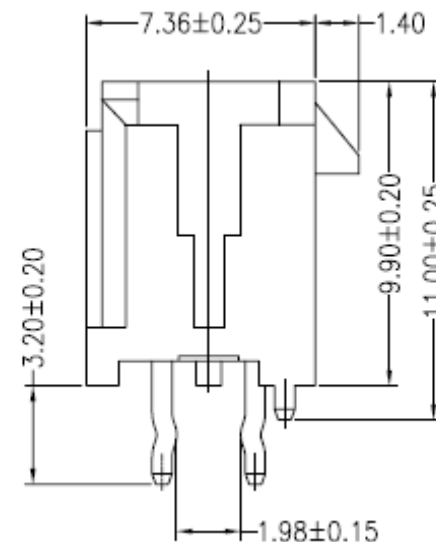
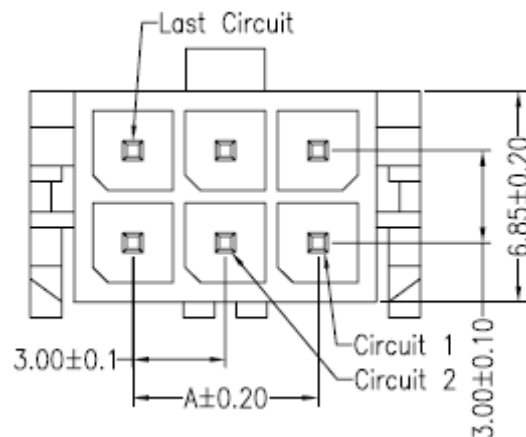
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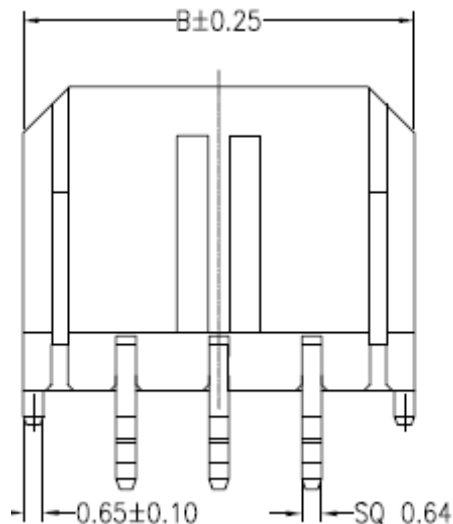
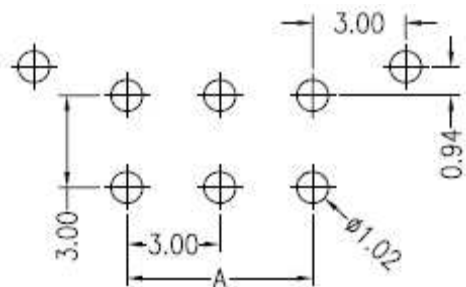
Specifications

Voltage Rating:	250VAC/DC
Current Rating	5,0A
Operating Temperature	-25°C ~ +85°C
Contact Resistance	10m Ohm max.
Withstanding Voltage	1500VAC/Minute
Insulation Resistance	1000M Ohm min.
Contact Material:	Brass
Contact Plating :	AU or Sn over Ni.
Insulator Material:	High Temperature Plastic UL94V-0

Drawing (dimensions all into mm)



Terminal Assembly Drawing



Wafer Serie T68Qxxx Pitch 3,00mm	
Part No.:	T68Q006
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	02.04.2009
APPD:	Schumi			FINISH	Jamy			Sheet No.	1 from 4

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email: info@edcon-components.com

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Dimension Informations about Wafer

	Dimension (mm)					
Pos.	A	B	C	D	E	F
2		6,65				
4	3,00	9,65				
6	6,00	12,65				
8	9,00	15,65				
10	12,00	18,65				
12	15,00	21,65				
14	18,00	24,65				
16	21,00	27,65				
18	24,00	30,65				
20	27,00	33,65				
22	30,00	36,65				
24	33,00	39,65				

	Dimension (mm)					
Pos.	A	B	C	D	E	F

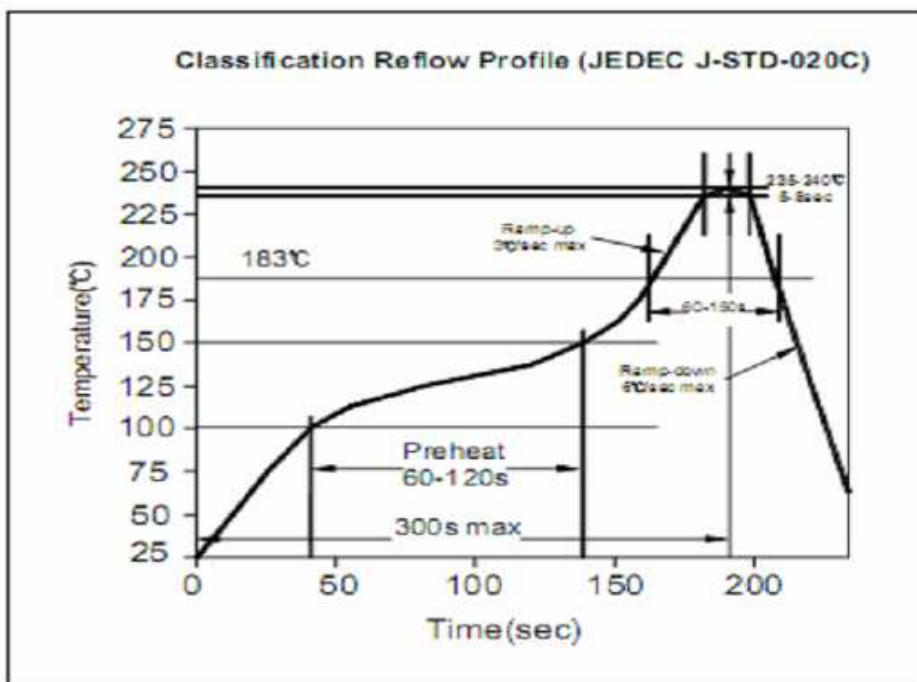
Wafer Serie T68Qxxx Pitch 3,00mm	
Part No.:	T68Q006
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	02.04.2009
APPD:	Schumi			FINISH	Jamy		Sheet No.	2 from 4	

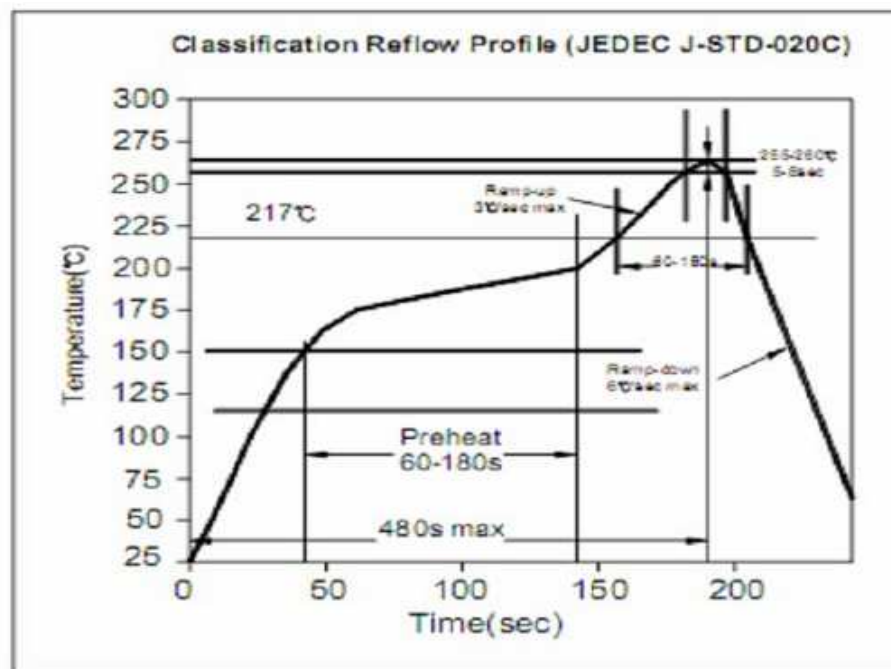


Soldering Profile

Lead Solder



Lead Free Solder



Wafer Serie T68Qxxx Pitch 3,00mm
Part No.: T68Q006
Customer:

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	02.04.2009
APPD:	Schumi			FINISH	Jamy		Sheet No.	3 from 4	

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Ordering Informations

Serie	Number of	Contact	Packing						
T68Q006	02	T	BU						

xx = Pos.	T= Tin Plated (Standard)	BU= Bulk (Standard)							
		TY= Tray Packing							
	G= Gold Flash Plated	TU= Tube Packing							

Wafer Serie T68Qxxx Pitch 3,00mm	
Part No.:	T68Q006
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	02.04.2009
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